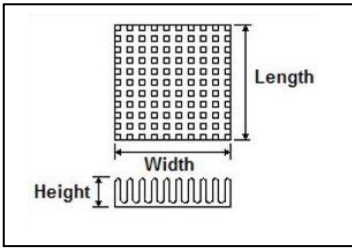
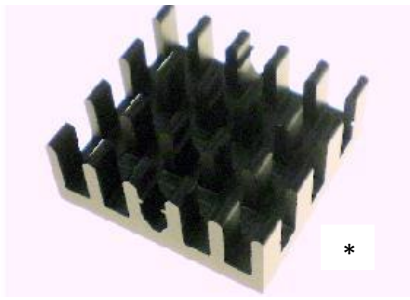




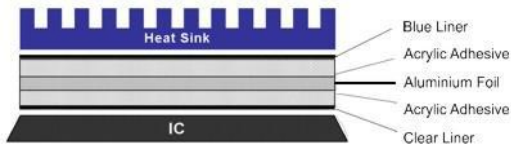
**Standard**



All ABL's BGA heatsinks are supplied with thermal tape

Model	Width	Length	Height	Pad	Wire Form	°C/W	
	[mm]	[mm]	[mm]	Size		Natural	Forced
				[mm]			2M/s
BGA-STD-010	13.5	13.0	10.0	12x12	-	27.00	14.50
BGA-STD-015	14.0	14.0	10.0	18x18	-	26.50	14.00
BGA-STD-020	21.0	21.0	9.0	20x20	-	24.50	13.00
BGA-STD-025	23.0	23.0	6.0	20x20	-	22.00	10.50
BGA-STD-030	27.0	27.0	6.0	20x20	WF700/WF300	20.00	10.00
BGA-STD-035	26.0	26.0	8.0	20x20	WF700/WF300	18.50	9.70
BGA-STD-040	27.0	27.0	6.0	20x20	WF700/WF300	16.00	10.20
BGA-STD-045	23.0	23.0	18.0	20x20	WF700/WF300	14.70	7.30
BGA-STD-050	20.0	20.0	19.1	18x18	-	14.00	5.80
*BGA-STD-055	25.9	23.9	10.0	20x20	WF700/WF300/WF151	14.00	6.00
BGA-STD-060	40.0	40.0	10.0	30x30	-	13.50	7.50
BGA-STD-065	27.8	27.8	11.2	20x20	WF700/WF300	12.20	5.80
BGA-STD-070	40.0	40.0	25.0	30x30	WF700/WF300/WF151	11.50	6.00
BGA-STD-075	40.0	40.0	23.0	18x18	WF700/WF300/WF151	11.00	5.60
BGA-STD-080	27.0	27.0	25.0	20x20	WF700/WF300/WF151	10.50	4.50
BGA-STD-085	30.7	30.7	14.1	20x20	WF700/WF300	10.00	5.20
BGA-STD-090	40.0	23.9	10.0	20x20	-	10.00	5.20
BGA-STD-095	40.0	40.0	10.0	18x18	WF700/WF300	9.70	4.00
BGA-STD-100	38.1	38.1	16.0	30x30	-	9.20	4.10
BGA-STD-105	35.0	35.0	18.0	30x30	WF700/WF300/WF151	9.20	5.20
BGA-STD-110	35.0	35.0	25.0	30x30	WF700/WF300/WF151	8.50	5.00
BGA-STD-115	40.0	40.0	18.0	30x30	WF700/WF300/WF151	8.20	5.10
BGA-STD-120	40.6	38.8	30.5	30x30	-	7.00	3.70

**Thermally Conductive Aluminium Foil**



All ABL's BGA heatsinks are supplied with thermal tape.

With excellent thermal conductivity, cushioning and gap filling properties, the pad is an ideal thermal interface material specifically designed for heat sink attachment to MPU, chip set and other plastic encapsulated components.

It consists of an aluminium foil backing coated, on both sides, with a very high temperature resistance acrylic adhesive. Due to its high heat performance and adhesive properties this tape can also be used to attach components to a vertical heatsink and to metal enclosure surfaces.

Colour	-	White
Backing Type / Thickness	Mm	Aluminium Foil / 0.10
Adhesive Type / Thickness	Mm	Arylic 0.075 (on clear liner side)
Total Thickness	mm	0,27
Adhesion	Kg/25mm	1,5
Thermal Conductivity	W/m-K	0,95
Thermal Resistance	°C-in <sup>2</sup> /W	0,2
Holding Power@23°C	Hour	>72
Holding Power @ 130°C	Hour	>2

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